L Number	Hits	Search Text	DB	Time stamp
9	62	(US-6425516-$ or US-5068714-$ or US-5543585-$ or US-6291270-$ or US-6180504-$ or US-6168972-$ or US-6118179-$ or US-5989982-$ or US-6380061-$ or US-6281591-$ or US-5656863-$ or US-5897337-$ or US-6410415-$ or US-6189208-$ or US-5747101-$ or US-5329423-$ or US-4818728-$ or US-6100114-$ or US-5704116-$ or US-5650667-$ or US-6355507-$ or US-5933713-$ or US-5869899-$ or US-5496775-$ or US-6288335-$ or US-6054772-$).did. or (US-5908317-$ or US-5824569-$ or US-5554887-$ or US-5579573-$ or US-5641113-$ or US-6225206-$ or US-5143865-$ or US-5824438-$ or US-6392143-$ or US-6093972-$ or US-5895229-$ or US-6388333-$ or US-6469374-$ or US-6239496-$ or US-6188127-$ or US-6063646-$ or US-6531782-$ or US-4868634-$ or US-6118670-$ or US-6051886-$ or US-4237522-$ or US-3611317-$ or US-3562592-$ or US-4254445-$ or US-6418490-$ or US-6555760-$ or US-6294828-$).did. or (US-6162660-$ or US-6130476-$ or US-5604379-$ or US-6337522-$ or US-6251766-$ or US-3839727-$ or US-6260264-$ or US-5956605-$ or US-5895976-$).did.	USPAT	2003/11/30 14:33
21	33	"5543585"	USPAT	2003/11/30 15:49
24	5	("5068714" | "5128746" | "5497938" | "5543585" | "5751068").PN.	USPAT	2003/11/30 14:35
25	18	("4676868" | "5030799" | "5218234" | "5355580" | "5442240" | "5488200" | "5543585" | "5600180" | "5621225" | "5641946" | "5650667" | "5659203" | "5703406" | "5704116" | "5710071" | "5751553" | "5956605" | "6022761").PN.	USPAT	2003/11/30 14:46
26	9	6168972.URPN.	USPAT	2003/11/30 14:49
29	12	("4724613" | "5496775" | "5672393" | "5888850" | "5933713" | "6063828" | "6100114" | "6168972" | "6172141" | "6245595" | "6248614" | "6255142").PN.	USPAT	2003/11/30 14:52
81	10	("5674785" | "5677566" | "5739585" | "5763939" | "5783461" | "5811879" | "5834945" | "5885849" | "5925930" | "5956605").PN.	USPAT	2003/11/30 15:30
82	15	("4182781" | "4970571" | "5196371" | "5258577" | "5468681" | "5468995" | "5478007" | "5485038" | "5486721" | "5489804" | "5491612" | "5493437" | "5521432" | "5561320" | "5674780").PN.	USPAT	2003/11/30 15:32
83	16	5925930.URPN.	USPAT	2003/11/30 15:33
128	3590	(polyimide (epoxy adj resin)) near2 (bonded bonding bond adher$4)	USPAT	2003/11/30 15:50
129	8176	(polyimide (epoxy adj resin)) near2 (bonded bonding bond adhesive adher$3)	USPAT	2003/11/30 15:50
130	5369	(polyimide (epoxy adj resin)) near2 adhesive	USPAT	2003/11/30 15:51
131	1865	((polyimide (epoxy adj resin)) near2 adhesive) and (chip die)	USPAT	2003/11/30 15:52
132	1117	(((polyimide (epoxy adj resin)) near2 adhesive) and (chip die)) and semiconductor	USPAT	2003/11/30 15:52
133	299	((polyimide (epoxy adj resin)) near2 adhesive) with (chip die)	USPAT	2003/11/30 15:52
134	249	(((polyimide (epoxy adj resin)) near2 adhesive) with (chip die)) and semiconductor	USPAT	2003/11/30 15:52

135	92	((((polyimide (epoxy adj resin)) near2 adhesive) with (chip die)) and semiconductor) and (bump ball) and solder	USPAT	2003/11/30 16:12
136	672	((polyimide (epoxy adj resin)) near2 (bonded bonding bond adhesive adher$3)) and (bump ball) and solder and (chip die)	USPAT	2003/11/30 16:13
137	580	(((polyimide (epoxy adj resin)) near2 (bonded bonding bond adhesive adher$3)) and (bump ball) and solder and (chip die)) not (((((polyimide (epoxy adj resin)) near2 adhesive) with (chip die)) and semiconductor) and (bump ball) and solder)	USPAT	2003/11/30 16:13
138	92	((((polyimide (epoxy adj resin)) near2 (bonded bonding bond adhesive adher$3)) and (bump ball) and solder and (chip die)) not (((((polyimide (epoxy adj resin)) near2 adhesive) with (chip die)) and semiconductor) and (bump ball) and solder)) and (csp (chip adj scale adj package)(chip adj sized adj package))	USPAT	2003/11/30 16:27
139	28	TAGUSA-YASUNOBU	USPAT	2003/11/30 16:52
140	5	MATSUBARA-KOJI	USPAT	2003/11/30 16:51
141	125	MATSUBARA-KOJI	USPAT; JPO	2003/11/30 16:52